

ELECTRONIC MATERIALS

CMP TECHNOLOGIES

ACESOL® - series Colloidal Silica CMP Slurry

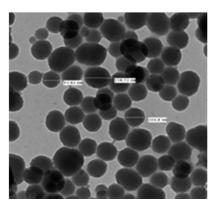
ACE NANOCHEM

ACESOL® WP100H (Wafer Stock Polishing Slurry)

DESCRIPTION

Acesol® slurries offer a complete solution for your polishing requirements based on the latest colloidal silica technology showing exceptional stability and high manufacturing reproducibility

TEM Image



Precisely Controlled ACESOL® Particles.

KEY FEATURES

- Non-agglomerating slurries with tight Particle distributions
- Enables high removal rates
- Low solid contents, excellent uniformity, no defect
- Products development for customized applications
- Individual, non-setting spherical particles

SPECIFICATION

Abrasive	Colloidal Silica
Mean Particle	70 -120 nm
Specific Gravity (20℃) g/cc	1.120
Solid Content (wt%)	20
Viscosity (25℃) cps	<5
pH (20℃)	11.15
Shelf life	1 Year

Metal impurity (Unit:ppm)

Metal	Result	Spec
Na	700	<1000
Al	85	<100
Fe	15	<30
Cr	ND	<0.5
Cu	23 (ppb)	<40(ppb)
Ni	27 (ppb)	<40(ppb)